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The applicant and/or attorney requests the date of deposit as the filing date. Depositor: Karen Cing-Mars
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Karen Cing-Mars 4/26/03
(Signature & date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : June 25, 2003
Pogge et al. : Group Art Unit:
Serial No. Not yet assigned : Examiner:
Filed: Herewith : IBM Corporation
This application is a Dept. 18G/Bldg. 300-482
division of: 2070 Route 52,
Serial No. 10/213,872 Hopewell Junction, NY 12533
Filed: August 6, 2002 :

Title: PROCESS FOR MAKING FINE
PITCH CONNECTIONS BETWEEN
DEVICES AND STRUCTURE MADE BY
THE PROCESS :

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P. O. Box 1450
Arlington, VA 22313-1450

Sir:

As a means of complying with the duty of disclosure set forth in 37 CFR 1.56, Applicants are hereby filing an Information Disclosure Statement pursuant to 37 CFR 1.97 and 37 CFR 1.98. The references listed are those which were cited in

Based on Serial No. 10/213,872

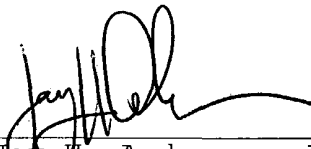
Applicants' parent patent application, Serial No. 09/669,531, issued as patent 6,444,560 on September 3, 2002, and Serial No. 10/213,872, CIP filed August 6, 2002.

A summary of all the references is made on Form PTO-1449, attached hereto. Pursuant to 37 CFR 1.98(d), copies of all the references are not being provided as they were previously cited and submitted in Applicants' parent Application noted above.

The Examiner is respectfully requested to consider each reference and initial a copy of Form PTO-1449 and return a copy of same to Applicants.

Respectfully submitted,

Pogge, et al.



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INFORMATION DISCLOSURE CITATION (Use several sheets if necessary) Page 1 of 3	Atty. Docket No. FIS9-2000-0134US3	Application No.
	Applicant H. BERNHARD POGGE	
	Filing Date	Group

U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	4 6 7 0 7 7 0	06/02/87	Tai			
	4 7 8 3 6 9 5	11/08/88	Eichelberger et al.			
	4 8 8 4 1 2 2	11/28/89	Eichelberger et al.			
	4 9 3 3 0 4 2	06/12/90	Eichelberger et al.			
	4 9 4 9 1 4 8	08/14/90	Bartelink			
	5 0 1 9 5 3 5	05/28/91	Wojarowski et al.			

FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	1 0 4 1 6 2 4	10/04/00	European Patent Office				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)

	J. Pilchowski et al., "Silicon MCM with Fully Integrated Cooling,"
	HDI Magazine, May 1998, p.48.
	J. Wolf et al., "System Integration for High Frequency Applications,"
	Intl. J. of Microelectronics and Electronic Packaging 21, 119 (1998).
	C.A. Armiento et al., "Gigabit Transmitter Array Modules on Silicon Waferboard," IEEE Transactions on Components, Hybrids and Manufacturing Technology 15, 1072 (1992).
	M. Töpper et al., "Embedding Technology--A Chip-First Approach Using BCB,"
	1997 Intl. Symposium on Advanced Packaging Materials, p. 11.

EXAMINER

DATE CONSIDERED

Examiner: Initial if reference considered, whether or not citation is in conformance with PEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form PTO-FB-A820

Also form PTO-1449)

Patent and Trademark Office-U.S. DEPARTMENT of COMMERCE
(June 8, 1999)

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

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Atty. Docket No.
FIS9-2000-0134 US3

Application No.

Applicant
H. BERNHARD POGGE

Filing Date

Group

U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	5 3 5 3 4 9 8	10/11/94	Fillion et al.			
	5 3 7 3 6 2 7	12/20/94	Grebe			
	6 1 1 0 8 0 6	08/29/00	Pogge			

FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Subclass	Translation	
					Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)

	Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and Actuators, p. 261.
	Robert Boudreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B, 21, 1070 (1998).
	Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998).
	R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume, Low Cost Electronics," Circuit World 21, 28 (1995).

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ATTY DOCKET NO.

FIS9-2000-0134US3

SERIAL NO.

APPLICANT(S)

H. BERNHARD POGGE

FILING DATE

GROUP

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*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6,025,638	02-15-00	POGGE ET AL.			
	6,066,513	05-23-00	POGGE ET AL.			
	5,998,868	12-07-99	POGGE ET AL.			
	6,087,199	07-11-00	POGGE ET AL.			
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	6,355,501	03-12-02	Fung et al.			

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						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

"A Novel Chip-Stack Package" - Solid State Technology, April 2002, www.solid-state.com, pp. S19-S22, Eric Beyne, IMEC, Leuven, Belgium

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